Abstracts

Laser Chip Separation Method for GaAs MMIC Wafers (1988 Vol. I [MWSYM])

E.H. Wong, R.B. Wylie and D.R. Johnson. "Laser Chip Separation Method for GaAs MMIC Wafers (1988 Vol. I [MWSYM])." 1988 MTT-S International Microwave Symposium Digest 88.1 (1988 Vol. I [MWSYM]): 103-106.

A chip separation process using a Nd-YAG laser with the wafer mounted on stretchable tape for machine sort and load has been developed for the GaAs MMIC wafers. This method is especially suitable for prototype masks with multiple chip design. One of the major advantages of this technique is that the laser can be programmed to cut any pattern desired such that the different circuits need not be laid out in a straight grid pattern as required for sawing. One hundred percent (100%) chip separation yield with no chipping or cracking has been demonstrated. The complete laser chip separation process will be described.

❑ Return to main document.